

Test 1

- (a) Plug in the 128k RAM pack to the RAM pack test jig.
- (b) Switch on the modified Z88 test jig.
- (c) Check that the current being drawn by the system is 100 mA \pm 20 mA.

Test 2

- (a) Plug in the 128k RAM pack to the RAM pack test jig.
- (b) Using the two SHIFT keys, switch the test rig OFF.
- (c) Monitor the supply current for a period of two minutes and check that the current at no time exceeds 0.8 mA.

3. REPAIR

3.1 General

3.1.1 Renewal of components should be carried out using recognised desoldering/heatsinking techniques to prevent damage to the component or to the printed circuit board. Note the following points:

- (a) When handling ICs take normal anti-static precautions. It is recommended that only a suitably earthed, low power soldering iron be used.
- (b) When renewing/replacing the plug-in IC (IC3) it is advisable to use the correct removal and insertion tools. Avoid contaminating the connection pins by handling them.
- (c) When replacing a keyboard assembly, ensure that the ribbon connectors are correctly aligned, fully inserted into the board connectors and are not kinked during insertion.
- (d) After repairing a 32k RAM pack, the cover should be swaged using a centre punch and a ?? lb hammer.
- (e) After any component has been renewed, the circuit board should be examined carefully to ensure that there are no solder splatters which may cause short circuits between tracks or connector pins.
- (f) LCD Display Handling Precautions
 - (1) The display modules consist of two thin glass plates with polarizers (with UV cut filters) which are easily damaged. Extreme care should be used when handling the display panel.